

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : SSB0-ZZ-0004

Description : SFP+ 2X2 Ass'y
Press-Fit
With Inner LightPipe
Contact Area : 15μ" min. Gold
Packing With Tray



Spec No.
SSB020010-00

Update Date
2020/6/9

Revision
A

Approved	Checked	Prepared



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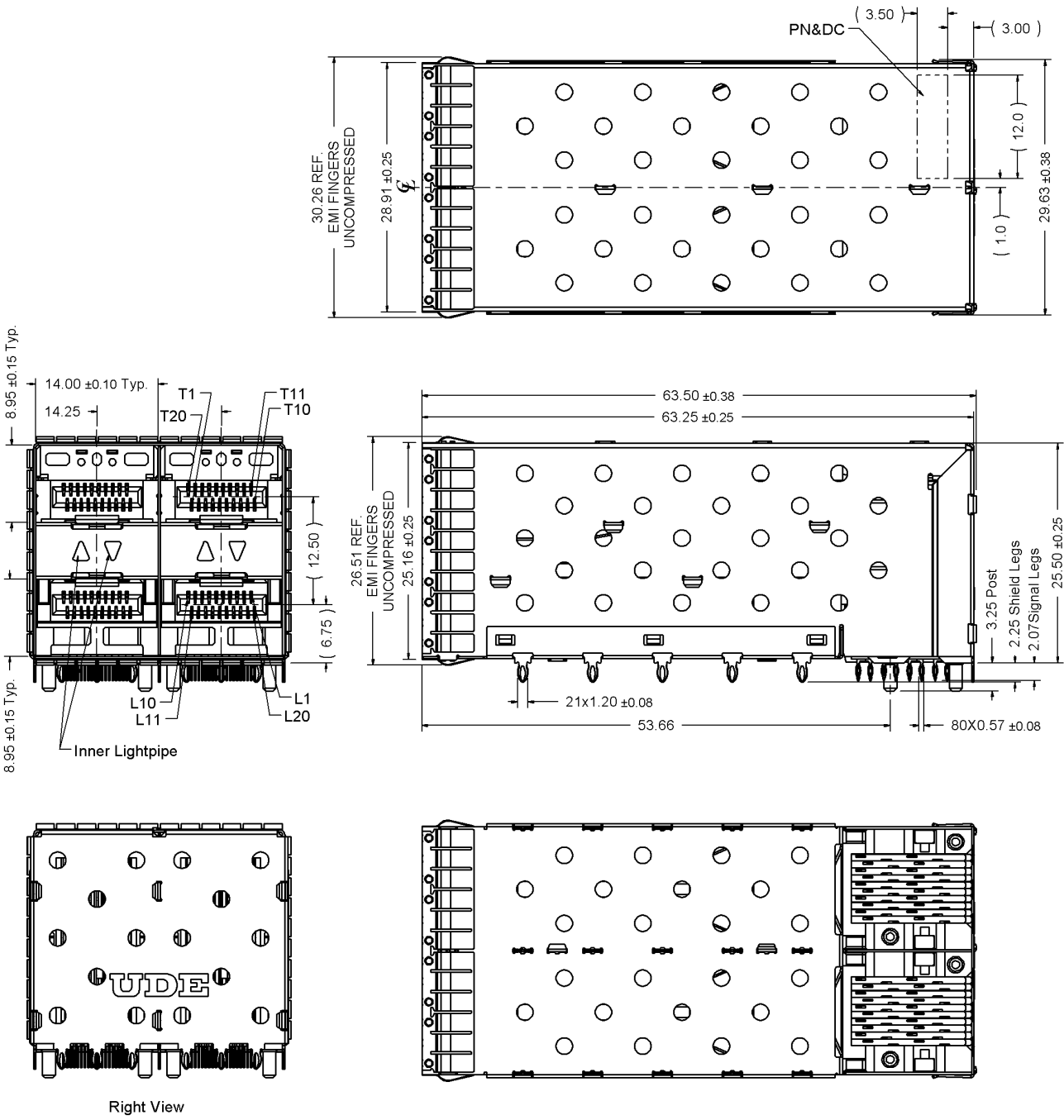
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1. MECHANICAL DIMENSION

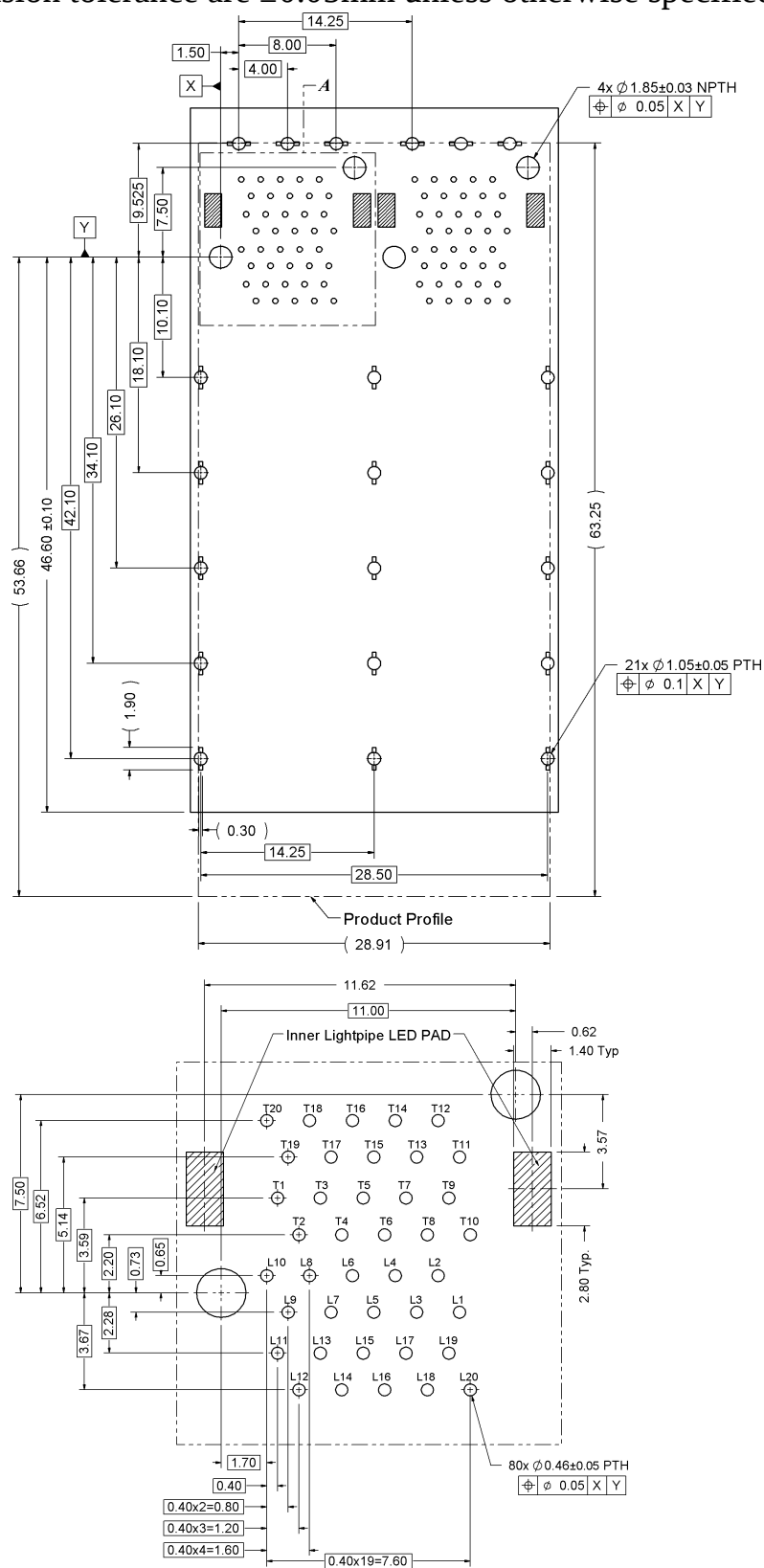
1.1 Product Dimension

Unit : mm	General Tolerance : X.X : ± 0.38 X.XX : ± 0.20
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1.2 Recommended PCB Layout

Component Side of Board

All dimension tolerance are $\pm 0.05\text{mm}$ unless otherwise specified細部放大圖 A
比例 5 : 1

NOTES:

1.RECOMMENDED THRU HOLE PLATING INCLUDES

HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)

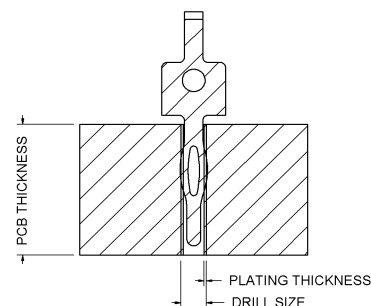
2.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USB.

3.HATCHED AREA IS PLACEMENT ZONE FOR LED,LED SHOULD BE

CENTERED WITHIN ZONE,RECOMMEND 0805 PACKAGE

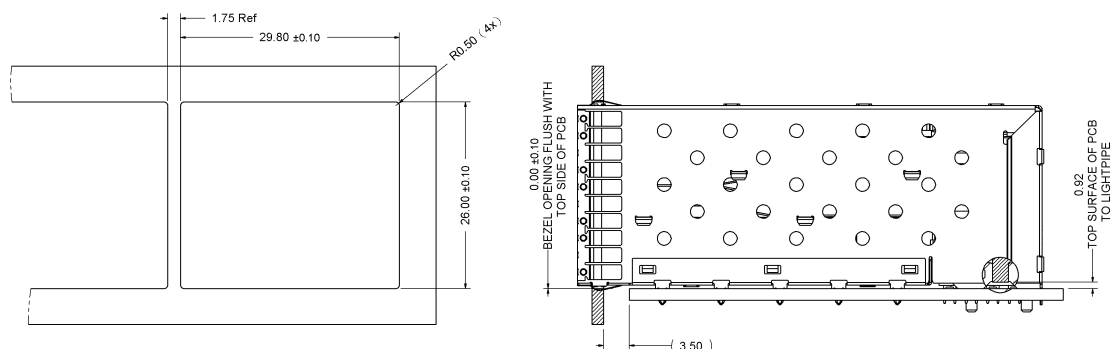
RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

PLATED THROUGH HOLE	1.05 SHIELD PINS	0.46 SIGNAL PINS
FINISHED HOLE DIAMETER	1.05±0.05	0.46±0.05
DRILLED HOLE DIAMETER	1.15	0.56
COPPER PLATING	0.025 min.	0.025 min.



RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

1.3 Recommended Panel Cutout



PRESS-FIT ASSEMBLIES

HAND PLACE USING PROPER SEATING FORCE TO ENGAGE ALL LEG TAILS INTO PLATED THRU-HOLES

ASSEMBLIES ARE TO BE SEATED PER THE INSTRUCTIONS ASSOCIATED WITH THE APPROPRIATE INSERTION TOOL

NOTE:UDE RECOMMENDS ONLY ONE CONNECTOR ASSEMBLY BE INSTALLED AT A TIME

ASSEMBLE INSERTION FORCE		
PORT SIZE	PCB FINISH	FORCE
2X2	Copper w/OSP	725±73N

1.4 Packing Information

12 pcs finished goods per tray

5 trays(60pcs finished goods) per master carton

2. REQUIREMENTS

2.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

2.2 Material

Top Shell&Bottom Shell : Copper Alloy,Thickness=0.25mm

RL Mid Ground: Copper Alloy,Thickness=0.25mm

UD Mid Ground: Copper Alloy,Thickness=0.25mm

Inner Spring : SUS304, Thickness=0.20mm

EMI Spring Finger : Ph.Bronze, Thickness=0.08mm

Connector Housing: LCP/BK,UL94V-0

Terminal: Ph.Bronze ,Thickness=0.20mm

Inner Lightpipe: PC,UL94V-0,Transparent

2.3 Finish :

EMI Spring Finger : 30μ" min. Nickel overall.

Terminal : Contact area 15μ"min. Gold Plating, 50μ"min. Nickel overall.

Solder Tail 30μ"min. Matte Tin, 50μ"min. Nickel overall.

2.4 Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : -55°C to +105°C

2.5 SFP+ specifications

Contact Current Rating: 0.5A (per contact)

Insulation Resistance : 100MΩ min.

Dielectric Withstanding Voltage : 300VDC @1min.

Insertion force : 40N MAX.

Extraction force : 12.5N MAX.

Durability : 100 cycles MIN.

Cage Retention (Latch strength) : 90N Min.

2.6 Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

2.7 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

4. Revision History

[illegible]